TOSHIBA CMOS Digital Integrated Circuit Silicon Monolithic

# TC74AC273P,TC74AC273F,TC74AC273FT

#### Octal D-Type Flip Flop with Clear

The TC74AC273 is an advanced high speed CMOS OCTAL D-TYPE FLIP FLOP fabricated with silicon gate and double-layer metal wiring C<sup>2</sup>MOS technology.

It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

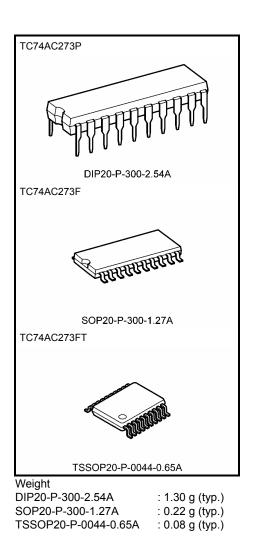
Information signals applied to D inputs are transferred to the Q output on the positive going edge of the clock pulse.

When the  $\overline{\text{CLR}}$  input is held "L", the Q outputs are at a low logic level independent of the other inputs.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

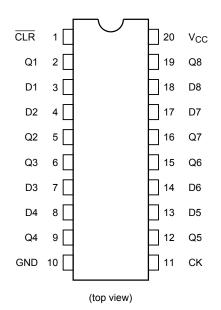
#### Features

- High speed:  $f_{max} = 170 \text{ MHz}$  (typ.) at  $V_{CC} = 5 \text{ V}$
- Low power dissipation:  $I_{CC}$  = 8  $\mu A$  (max) at Ta = 25°C
- High noise immunity:  $V_{\text{NIH}} = V_{\text{NIL}} = 28\% V_{\text{CC}}$  (min)
- Symmetrical output impedance:  $|IOH| = IOL = 24 \text{ mA (min) Capability of driving 50 }\Omega$  transmission lines.
- Balanced propagation delays:  $t_{pLH} \simeq t_{pHL}$
- Wide operating voltage range: VCC (opr) = 2 V to 5.5 V
- Pin and function compatible with 74F273



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# **Pin Assignment**

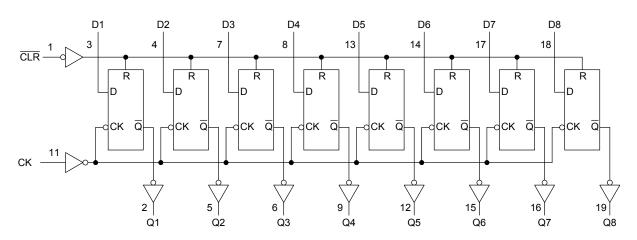


### Truth Table

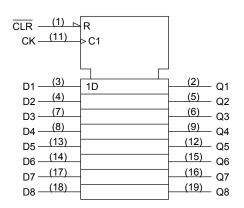
Inputs			Output	Function		
CLR	D	СК	Q	Function		
L	Х	Х	L	Clear		
н	L		L	_		
Н	Н		Н	_		
Н	Х		Qn	No Change		

X: Don't care

# System Diagram



# IEC Logic Symbol



2007-10-01

### Absolute Maximum Ratings (Note 1)

Characteristics	Symbol	Rating	Unit
Supply voltage range	V <sub>CC</sub>	–0.5 to 7.0	V
DC input voltage	V <sub>IN</sub>	-0.5 to V <sub>CC</sub> + 0.5	V
DC output voltage	V <sub>OUT</sub>	-0.5 to V <sub>CC</sub> + 0.5	V
Input diode current	IIK	±20	mA
Output diode current	I <sub>ОК</sub>	±50	mA
DC output current	IOUT	±50	mA
DC V <sub>CC</sub> /ground current	Icc	±200	mA
Power dissipation	PD	500 (DIP) (Note 2)/180 (SOP/TSSOP)	mW
Storage temperature	T <sub>stg</sub>	–65 to 150	°C

Note 1: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 2: 500 mW in the range of Ta = -40 to  $65^{\circ}$ C. From Ta = 65 to  $85^{\circ}$ C a derating factor of -10 mW/°C should be applied up to 300 mW.

Characteristics	Symbol	Rating	Unit	
Supply voltage	V <sub>CC</sub>	2.0 to 5.5	V	
Input voltage	V <sub>IN</sub>	0 to V <sub>CC</sub>	V	
Output voltage	V <sub>OUT</sub>	0 to V <sub>CC</sub>	V	
Operating temperature	T <sub>opr</sub> –40 to 85		°C	
Input rise and fall time	dt/dV	0 to 100 (V_{CC} = 3.3 $\pm$ 0.3 V)	ns/V	
	u/uv	0 to 20 (V_{CC} = 5 $\pm$ 0.5 V)		

#### **Operating Ranges (Note)**

Note: The operating ranges must be maintained to ensure the normal operation of the device. Unused inputs must be tied to either VCC or GND.

### **Electrical Characteristics**

#### **DC Characteristics**

Characteristics	Symbol	Test Condition		-	Га = 25°(	)	Ta = -40 to 85°C		Unit			
Characteriotico					V <sub>CC</sub> (V)	Min	Тур.	Max	Min	Max	Offic	
				2.0	1.50	_	_	1.50	_			
High-level input voltage	VIH		—		3.0	2.10	—	—	2.10	—	V	
				5.5	3.85	—	_	3.85	—			
					2.0			0.50		0.50		
Low-level input voltage	VIL	—		3.0	—	—	0.90		0.90	V		
					5.5		—	1.65		1.65		
	Vон	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -50 μA		2.0	1.9	2.0	_	1.9	_	v	
					3.0	2.9	3.0	—	2.9	—		
High-level output					4.5	4.4	4.5	—	4.4	—		
voltage			$I_{OH} = -4 \text{ mA}$		3.0	2.58	_	_	2.48	_	V	
			$I_{OH} = -24 \text{ mA}$		4.5	3.94	—	—	3.80	—		
			$I_{OH} = -75 \text{ mA}$	(Note)	5.5		—	_	3.85	—		
	V <sub>OL</sub>				2.0		0.0	0.1		0.1		
			$I_{OL} = 50 \ \mu A$		3.0	_	0.0	0.1		0.1		
Low-level output		V <sub>IN</sub> = V <sub>IH</sub> or			4.5		0.0	0.1		0.1	v	
voltage		VIL	I <sub>OL</sub> = 12 mA		3.0	_	—	0.36		0.44	v	
			$I_{OL} = 24 \text{ mA}$		4.5	—	—	0.36		0.44		
			$I_{OL} = 75 \text{ mA}$	(Note)	5.5			_		1.65		
Input leakage current	I <sub>IN</sub>	$V_{IN} = V_{CC}$ or GND		5.5	_		±0.1		±1.0	μA		
Quiescent supply current	ICC	$V_{IN} = V_{CC}$ or GND		5.5		_	8.0	_	80.0	μA		

Note: This spec indicates the capability of driving 50  $\Omega$  transmission lines. One output should be tested at a time for a 10 ms maximum duration.

#### Timing Requirements (input: $t_r = t_f = 3 \text{ ns}$ )

Characteristics	Symbol	Test Condition	Ta = 25°C	Ta = -40 to 85°C	Unit	
			$V_{CC}(V)$	Limit	Limit	
Minimum pulse width	t <sub>w (L)</sub>		$\textbf{3.3}\pm\textbf{0.3}$	8.0	8.0	
(CK)	t <sub>w (H)</sub>	—	$5.0 \pm 0.5$	5.0	5.0	ns
Minimum pulse width	4		$\textbf{3.3}\pm\textbf{0.3}$	7.5	7.5	
( CLR )	<sup>t</sup> w (L)	—	$5.0\pm0.5$	5.0	5.0	ns
Minimum oct un time	t <sub>s</sub>	_	$\textbf{3.3}\pm\textbf{0.3}$	8.5	8.5	ns
Minimum set-up time			$5.0\pm0.5$	4.5	4.5	
Minimum hold time	t <sub>h</sub>		$\textbf{3.3}\pm\textbf{0.3}$	0.0	0.0	
Minimum hold time		—	$5.0\pm0.5$	0.0	0.0	ns
Minimum removal time			$\textbf{3.3}\pm\textbf{0.3}$	7.0	7.0	
( CLR )	t <sub>rem</sub>		$5.0\pm0.5$	3.5	3.5	ns

#### AC Characteristics (C<sub>L</sub> = 50 pF, R<sub>L</sub> = 500 $\Omega$ , input: t<sub>r</sub> = t<sub>f</sub> = 3 ns)

Characteristics	Symbol	Test Condition		Ta = 25°C			Ta = -40 to 85°C		Unit
	- ,		V <sub>CC</sub> (V)	Min	Тур.	Max	Min	Max	
Propagation delay time (CK-Q)	t <sub>pLH</sub> t <sub>pHL</sub>	_	$\begin{array}{c} 3.3\pm0.3\\ 5.0\pm0.5\end{array}$	_	9.0 6.5	15.8 9.6	1.0 1.0	18.0 11.0	ns
Propagation delay time ( CLR -Q)	t <sub>pHL</sub>	_	$\begin{array}{c} 3.3\pm0.3\\ 5.0\pm0.5\end{array}$		8.0 5.9	14.0 9.2	1.0 1.0	16.0 10.5	ns
Maximum clock frequency	f <sub>max</sub>	_	$\begin{array}{c} 3.3\pm0.3\\ 5.0\pm0.5\end{array}$	55 90	110 150		55 90		MHz
Input capacitance	C <sub>IN</sub>	_		_	5	10	_	10	pF
Power dissipation capacitance	C <sub>PD</sub>		(Note)	_	40	_	_	_	pF

Note: C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation:

 $I_{CC (opr)} = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}/8 (per F/F)$ 

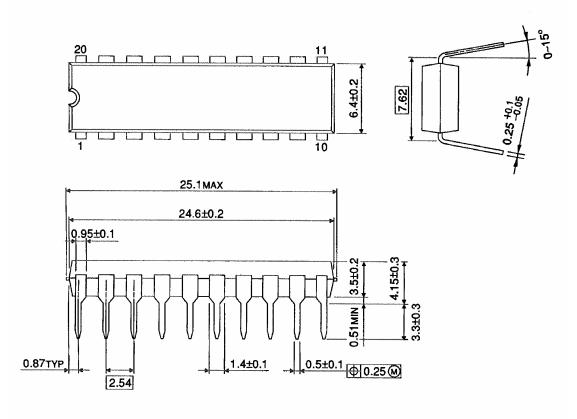
And the total  $C_{PD}$  when n pcs. of flip flop operate can be gained by the following equation:

 $C_{PD}$  (total) = 29 + 11·n

## Package Dimensions

DIP20-P-300-2.54A

Unit : mm

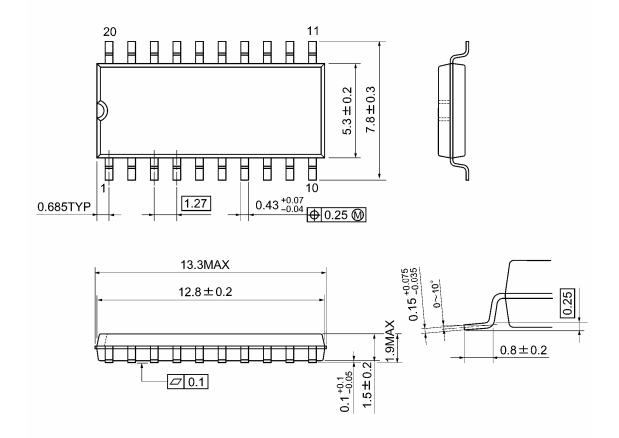


Weight: 1.30 g (typ.)

## **Package Dimensions**

SOP20-P-300-1.27A

Unit: mm

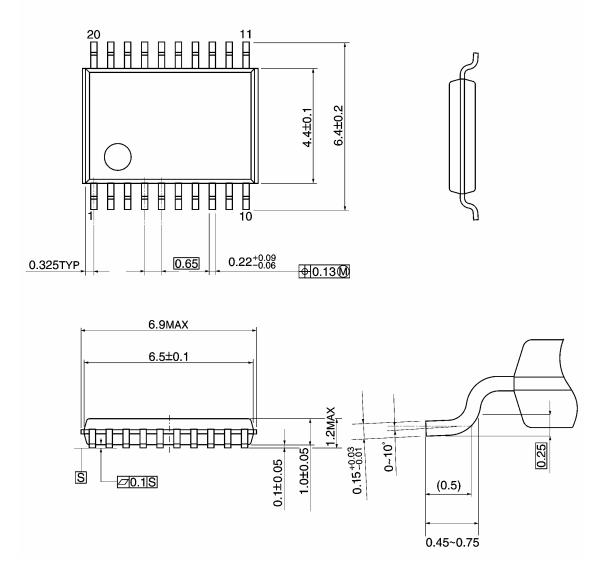


Weight: 0.22 g (typ.)

### **Package Dimensions**

TSSOP20-P-0044-0.65A

Unit: mm



Weight: 0.08 g (typ.)

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20070701-EN GENERAL

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